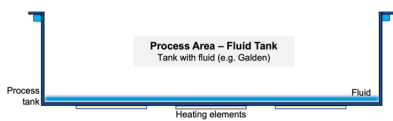


# Vapour Phase Reflow Machine Lineup

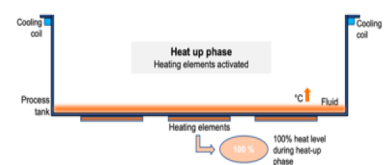
Vapour Phase Reflow ovens are used in all kind of electronic manufacturing sectors, where reliable solder joints are necessary. Excellent heat transfer that is up to 10 times faster than in convection ovens is just one of the efficient characteristics of those machines. The reflow process takes place in an inert atmosphere where no oxidation takes place including no shadowing effects. Heavy populated boards with a high mixture of components can be easily soldered without overheating of small chip surface mounted parts. The technology implemented by IBL includes a special patented transport system throughout the complete lineup. Continuous temperature monitoring within the process chamber allow setting of profiles with practically no  $\Delta T$ .

## Simple and effective solder process all in one

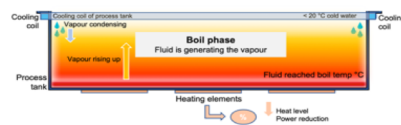
Step 1  
Process chamber with cold fluid.



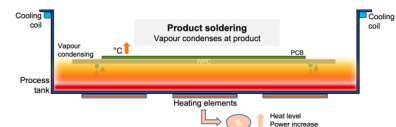
Step 2  
Heating elements warm up the fluid.



Step 3  
Vapour begins to rise generating an inert blanket.

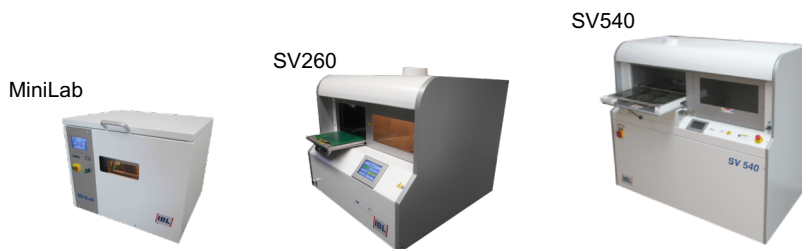


Step 4  
Product enters the solder chamber and is lowered into the vapour blanket.



## Economy Series batch

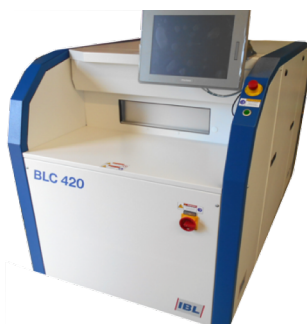
The economy line represents the entry level of IBL's vapour phase machines and is perfect for small series production, prototyping just as well as for rework purposes.



Machine	Max. board sizes (L x D x H)
MiniLab	304 x 274 x 80 mm
SV260	300 x 260 x 70 mm
SV540	540 x 360 x 80 mm

## Premium Series batch

The premium line batch series offers many additional features that are not included in the economy range of machines. The 15" HMI touch screen gives the user a comfortable and easy access to all of the functions. Permanent data collection together with an unlimited program memory are just a few of the features.



Intelligent Profiling System (IPS) gives the user the possibility of setting up profiles fast and efficient leading to high quality results without the need of reworking. Low power consumption, small footprint and low medium consumption are all features making this machine very environment friendly. Many additional options available.

Machine	Max. board sizes (L x D x H)
BLC420	450 x 540 x 80 mm
BLC620	650 x 540 x 80 mm
BLC820	850 x 540 x 80 mm

## Premium Series Inline

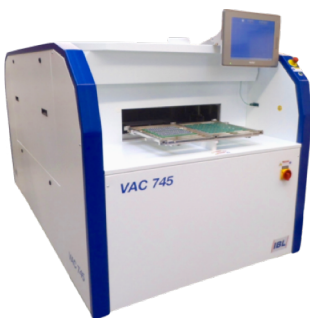


These machines can be fully integrated in an inline production with the same features as the BLC series. The boards are transported onto a work piece carrier and then moved into the process chamber. After soldering and cooling down the boards exit one after the other according to the FIFO principle. These machines can also be used in batch mode.

Machine	Max. PCB sizes inline mode	Max. PCB sizes batch mode
BLC620i	630 x 400 x 55 mm	650 x 540 x 80 mm
BLC820i	630 x 400 x 55 mm	850 x 540 x 80 mm

Hence: the overall capacity of the work piece carrier is larger than the largest size of a single board that can be fed onto the conveyor.

## Vacuum Series Batch



Reduction of voids can be reached with the help of vacuum. The vacuum chamber is located inside of the process chamber with a patented in vapour vacuum technology. Can also be used without vacuum function.

Machine	Max. PCB sizes with vacuum	Max. PCB sizes without vacuum
VAC745	635 x 444 x 70 mm	635 x 444 x 80 mm
VAC765	635 x 644 x 70 mm	635 x 644 x 80 mm

Hence: the use of the vacuum chamber limits the height of board. Other models existing on request.

## Vacuum Series Inline



VAC745HDxi

The VAC inline range is available either with one or two work piece carriers. Can also be used in batch mode and without vacuum function. Full traceability, data annalysis and many additional options available.

VAC745i



Machine	Max. PCB sizes with vacuum	Max. PCB sizes w/o vacuum	Max. PCB sizes w/o vacuum in batch mode
VAC745i	635 x 400 x 50 mm	635 x 400 x 60 mm	635 x 440 x 80 mm
VAC765i	635 x 400 x 50 mm	635 x 400 x 60 mm	635 x 640 x 80 mm
VAC745HDxi	630 x 400 x 45 mm	630 x 400 x 55 mm	635 x 444 x 75 mm

Hence: when used in batch mode refer to table for batch series with vacuum. Other transport widths also available.

## Premium Inline Series high volume

CX800



Machine with two work piece carriers can also be used in a batch mode reaching cycle times of 20 seconds per assembly.

Machine	Max. board sizes (L x D x H)
CX600	680 x 305 x 45 mm
CX800	680 x 510 x 45 mm

Hence: in batch mode board height 65mm

\*\*\* Specifications subject to change without prior notice\*\*\*

D1E120-Overview-E-211103